RELIABILITY REPORT

FOR

MAX3992UTG+

PLASTIC ENCAPSULATED DEVICES

July 21, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
Ken Wendel
Quality Assurance
Director, Reliability Engineering

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Conclusion

The MAX3992UTG+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. ....Device Description

II. ....Manufacturing Information

III. ....Packaging Information

.....Attachments

V. ....Quality Assurance Information

VI. ....Reliability Evaluation

IV. ....Die Information

I. Device Description

A. General

The MAX3992 is a 10Gbps clock and data recovery (CDR) with equalizer IC for XFP optical transmitters. The MAX3992 and the MAX3991 (CDR with limiting amplifier) form a signal conditioner chipset for use in XFP transceiver modules. The chipset is XFI compliant and offers multirate operation for data rates from 9.95Gbps to 11.1Gbps.

The MAX3992 recovers the data for up to 12 inches of FR-4 and one connector without the need for a standalone equalizer. The phase-locked loop is optimized for jitter tolerance in SONET, Ethernet, and Fibre-Channel applications. Low jitter generation of 4mUIRMS leaves adequate margin for meeting SONET jitter requirements at the optical output.

An AC-based power detector asserts the loss-of-signal (LOS) output when the input signal is removed. An external reference clock, with frequency equal to 1/64 or 1/16 of the serial data rate, is used to aid in frequency acquisition. A loss-of-lock (LOL) indicator is provided to indicate the lock status of the receiver PLL.

The MAX3992 is available in a 4mm x 4mm, 24-pin QFN package. It consumes 356mW from a single +3.3V supply and operates over a 0°C to +85°C temperature range.

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II. Manufacturing Information

A. Description/Function:	10Gbps Clock and Data Recovery with Equalizer
B. Process:	F120
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	China, Thailand, Malaysia
F. Date of Initial Production:	October 23, 2004

III. Packaging Information

A. Package Type:	24-pin TQFN 4x4
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-1124
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	48°C/W
K. Single Layer Theta Jc:	2.7°C/W
L. Multi Layer Theta Ja:	36°C/W
M. Multi Layer Theta Jc:	2.7°C/W

IV. Die Information

A. Dimensions:	100 X 100 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Au with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn) Metal 1, 2 & 3 5.6 microns (as drawn) Metal 4
F. Minimum Metal Spacing:	1.6 microns (as drawn) Metal 1, 2 & 3, 4.2 microns (as drawn) Metal 4
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 188 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 5.7 \times 10^{-9}$

λ = 5.7 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the F120 Process results in a FIT Rate of 0.33 @ 25C and 5.73 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The HD46 die type has been found to have all pins able to withstand a HBM transient pulse of +/-500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

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Table 1
Reliability Evaluation Test Results

MAX3992UTG+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	188	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

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